

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	570	L4 and @pd>="20090301"	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
L4	10113	L1 L2 L3	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
L3	5492	356/237.1-237.6.ccls.	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
L2	1033	348/86,87,125,126.ccls.	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
L1	4594	382/141,143-152.ccls.	US-PGPUB; USPAT	OR	ON	2009/10/12 09:45
S83	18	(CMP (chemical near2 mechanical near2 planarization)) near5 (while during) near5 imag\$4	US-PGPUB; USPAT	OR	ON	2009/10/10 13:07
S82	23	S81 and @ad<"20000430"	US-PGPUB; USPAT	OR	ON	2009/10/10 13:02
S81	176	S80 and (rotat\$4)	US-PGPUB; USPAT	OR	ON	2009/10/10 13:01
S80	313	S79 and (imag\$4 same thick \$5)	US-PGPUB; USPAT	OR	ON	2009/10/10 13:00
S79	1088	S78 and ((camera ccd imag \$4) near10 laser)	US-PGPUB; USPAT	OR	ON	2009/10/10 12:59
S78	82972	(CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/10 12:59
S77	1	"6186877".pn.	US-PGPUB; USPAT	OR	ON	2009/10/08 17:34
S76	20	S75 and (imag\$4 near5 (while dur\$4) near5 (rotat \$4))	US-PGPUB; USPAT	OR	ON	2009/10/08 17:08
S75	82972	(CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 17:08
S74	23	S73 and (imag\$4)	US-PGPUB; USPAT	OR	ON	2009/10/08 16:55
S73	78	S72 and @ad<"20000430"	US-PGPUB; USPAT	OR	ON	2009/10/08 16:55
S72	497	S71 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 16:55

S71	15168	((speed velocit\$4) near5 (object substrate semiconductor wafer die) near5 (motion moving movement))	US-PGPUB; USPAT	OR	ON	2009/10/08 16:55
S70	23	S61 and (high near3 speed near3 (imag\$4 camera cod))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:14
S69	6	S68 and (imag\$4 near10 (film layer near5 (thick\$5)))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:12
S68	334	S60 and (CMP (chemical near2 mechanical near2 planarization) same imag\$4). ab.	US-PGPUB; USPAT	OR	ON	2009/10/08 14:12
S67	134	S66 and (imag\$4 near10 (film layer near5 (thick\$5)))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:11
S66	2455	S60 and (CMP (chemical near2 mechanical near2 planarization) same imag\$4)	US-PGPUB; USPAT	OR	ON	2009/10/08 14:11
S65	11	S60 and ((CMP (chemical near2 mechanical near2 planarization)) same (imag \$4 near10 (film layer near5 (thick\$5))))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:09
S64	134	S61 and (imag\$4 near10 (film layer near5 (thick\$5)))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:03
S63	64	S61 and S62	US-PGPUB; USPAT	OR	ON	2009/10/08 14:02
S62	42435	(imag\$4 near10 (thickness))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:02
S61	2482	S60 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:01
S60	15487	((rotat\$4 RPM) near5 (speed velocit\$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/08 14:01
S59	1	"6159073".pn.	US-PGPUB; USPAT	OR	ON	2009/10/08 13:36
S58	1	"5738574".pn.	US-PGPUB; USPAT	OR	ON	2009/10/08 13:21
S57	30	S55 and S56	US-PGPUB; USPAT	OR	ON	2009/10/08 13:12
S56	141526	((speed velocit\$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/08 13:12
S55	50	("5640242").URPN.	USPAT	OR	ON	2009/10/08 13:09

S54	6	("5333049"   "5409538"   "5413941"   "5436725"   "5452953"   "5486701").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/08 13:09
S53	1	"5640242".pn.	US-PGPUB; USPAT	OR	ON	2009/10/08 13:09
S52	10	S51 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 13:01
S51	249	((linea\$3 near5 (speed velocit \$4) near5 (object substrate semiconductor wafer die)) same ((imag\$4 video frame))	US-PGPUB; USPAT	OR	ON	2009/10/08 13:01
S50	6	((linea\$3 near5 (speed velocit \$4) near5 (object substrate semiconductor wafer die)) same ((imag\$4 video frame) near5 rate)	US-PGPUB; USPAT	OR	ON	2009/10/08 12:58
S49	251	S48 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:57
S48	2390	((linea\$3 near5 (speed velocit \$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:56
S47	78	S46 and @ad<"20000430"	US-PGPUB; USPAT	OR	ON	2009/10/08 12:55
S46	497	S45 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:55
S45	15168	((speed velocit\$4) near5 (object substrate semiconductor wafer die) near5 (motion moving movement))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:54
S44	40	S43 and @ad<"20000430"	US-PGPUB; USPAT	OR	ON	2009/10/08 12:51
S43	240	S40 and ((thick\$5 dimension) near5 (measur\$6 determin\$6) near5 (imag\$4 frame))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:51
S42	218	S40 and ((thick\$5 dimension) near5 (measur\$6 determin\$6) near5 (image frame))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:50
S41	868	S40 and ((thick\$5 dimension) near5 (measur\$6 determin\$6))	US-PGPUB; USPAT	OR	ON	2009/10/08 12:50

S40	7476	((speed velocit\$4) near5 (object substrate semiconductor wafer die)) near10 (imag\$4 video\$4)	US-PGPUB; USPAT	OR	ON	2009/10/08 12:49
S39	33	S38 and ((speed velocit\$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/07 15:44
S38	99	S26 S27 S28 S29 S30 S31 S32 S33 S34 S35 S36	US-PGPUB; USPAT	OR	ON	2009/10/07 15:34
S37	10	US-5795495-\$.D.ID. OR US-5861055-\$.D.ID. OR US-5865666-\$.D.ID. OR US-5868608-\$.D.ID. OR US-5882244-\$.D.ID. OR US-5888120-\$.D.ID. OR US-5893756-\$.D.ID. OR US-5931719-\$.D.ID. OR US-5948697-\$.D.ID. OR US-5957757-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:29
S36	10	US-5795495-\$.D.ID. OR US-5861055-\$.D.ID. OR US-5865666-\$.D.ID. OR US-5868608-\$.D.ID. OR US-5882244-\$.D.ID. OR US-5888120-\$.D.ID. OR US-5893756-\$.D.ID. OR US-5931719-\$.D.ID. OR US-5948697-\$.D.ID. OR US-5957757-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:29
S35	11	US-5722875-\$.D.ID. OR US-5722877-\$.D.ID. OR US-5725417-\$.D.ID. OR US-5736462-\$.D.ID. OR US-5738567-\$.D.ID. OR US-5741171-\$.D.ID. OR US-5747380-\$.D.ID. OR US-5755614-\$.D.ID. OR US-5762536-\$.D.ID. OR US-5762537-\$.D.ID. OR US-5777739-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:28
S34	11	US-5691253-\$.D.ID. OR US-5695660-\$.D.ID. OR US-5700180-\$.D.ID. OR US-5702292-\$.D.ID. OR US-5704987-\$.D.ID. OR US-5705320-\$.D.ID. OR US-5705435-\$.D.ID. OR US-5710076-\$.D.ID. OR US-5712185-\$.D.ID. OR US-5716873-\$.D.ID. OR US-5720845-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:28

S33	11	US-5660672-\$.D.ID. OR US-5663101-\$.D.ID. OR US-5663797-\$.D.ID. OR US-5664987-\$.D.ID. OR US-5667424-\$.D.ID. OR US-5667433-\$.D.ID. OR US-5667629-\$.D.ID. OR US-5668063-\$.D.ID. OR US-5670410-\$.D.ID. OR US-5672091-\$.D.ID. OR US-5674784-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:27
S32	11	US-5626715-\$.D.ID. OR US-5627110-\$.D.ID. OR US-5637185-\$.D.ID. OR US-5639388-\$.D.ID. OR US-5643046-\$.D.ID. OR US-5643050-\$.D.ID. OR US-5644221-\$.D.ID. OR US-5645682-\$.D.ID. OR US-5647952-\$.D.ID. OR US-5656229-\$.D.ID. OR US-5658183-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:26
S31	11	US-5492594-\$.D.ID. OR US-5516400-\$.D.ID. OR US-5531861-\$.D.ID. OR US-5559428-\$.D.ID. OR US-5561541-\$.D.ID. OR US-5595526-\$.D.ID. OR US-5597442-\$.D.ID. OR US-5597590-\$.D.ID. OR US-5609511-\$.D.ID. OR US-5614446-\$.D.ID. OR US-5624304-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:25
S30	11	US-5321304-\$.D.ID. OR US-5337015-\$.D.ID. OR US-5362669-\$.D.ID. OR US-5385866-\$.D.ID. OR US-5389194-\$.D.ID. OR US-5399234-\$.D.ID. OR US-5403228-\$.D.ID. OR US-5405806-\$.D.ID. OR US-5439551-\$.D.ID. OR US-5449314-\$.D.ID. OR US-5483568-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:24

S29	11	US-5321304-\$.D.ID. OR US-5337015-\$.D.ID. OR US-5362669-\$.D.ID. OR US-5385866-\$.D.ID. OR US-5389194-\$.D.ID. OR US-5399234-\$.D.ID. OR US-5403228-\$.D.ID. OR US-5405806-\$.D.ID. OR US-5439551-\$.D.ID. OR US-5449314-\$.D.ID. OR US-5483568-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:24
S28	11	US-5196353-\$.D.ID. OR US-5222329-\$.D.ID. OR US-5240522-\$.D.ID. OR US-5245790-\$.D.ID. OR US-5245794-\$.D.ID. OR US-5258093-\$.D.ID. OR US-5265378-\$.D.ID. OR US-5271798-\$.D.ID. OR US-5272115-\$.D.ID. OR US-5308438-\$.D.ID. OR US-5310455-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:24
S27	11	US-3734620-\$.D.ID. OR US-3748014-\$.D.ID. OR US-4312732-\$.D.ID. OR US-4374915-\$.D.ID. OR US-4632724-\$.D.ID. OR US-4689491-\$.D.ID. OR US-4793895-\$.D.ID. OR US-5036015-\$.D.ID. OR US-5081421-\$.D.ID. OR US-5151584-\$.D.ID. OR US-5169491-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:22
S26	1	"6247998".pn.	US-PGPUB; USPAT	OR	ON	2009/10/07 15:20
S25	6	US-2408764-\$.D.ID. OR US-4745608-\$.D.ID. OR US-6229272-\$.D.ID. OR US-6248995-\$.D.ID. OR US-6374053-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:18
S24	6	US-2408764-\$.D.ID. OR US-4745608-\$.D.ID. OR US-6229272-\$.D.ID. OR US-6248995-\$.D.ID. OR US-6374053-\$.D.ID.	US-PGPUB; USPAT; USOCR	OR	ON	2009/10/07 15:18
S23	3	S22 and (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:16
S22	1443	(imag\$4 near5 (speed velocit \$4) near5 (object substrate semiconductor wafer die) near5 (motion moving movement))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:13

S21	7	S17 and ((speed velocit\$4) near5 (object substrate semiconductor wafer die) near5 (motion moving movement))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:11
S20	62	S17 and ((speed velocit\$4) near5 (object substrate semiconductor wafer die))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:10
S19	29	S17 and ((speed velocit\$4) near5 (object substrate))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:07
S18	105	S17 and ((speed velocit\$4) same (image))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:06
S17	521	thick\$5 same (CMP (chemical near2 mechanical near2 planarization)) same (imag\$4))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:05
S16	26169	thick\$5 same (CMP (chemical near2 mechanical near2 planarization))	US-PGPUB; USPAT	OR	ON	2009/10/07 14:05

### EAST Search History (Interference)

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